

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1385in#pbf

(Engineering Calculation)

PDIP

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**TOTAL MASS (g) : 1.202708**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003860	1000000	3209.42358398		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.345150	975000	286977.3125		
		Iron (Fe)	7439-89-6	0.008496	24000	7064.05761719		
		Phosphorus (P)	7723-14-0	0.000106	300	88.1344223022		
		Zinc (Zn)	7440-66-6	0.000248	700	206.201293945		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.354000</b>	<b>1000000</b>	<b>294335.71875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.027934	1000000	23226.1445312		
		<b>External Plating Total:</b>				<b>0.027934</b>	<b>1000000</b>	<b>23226.1445312</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.002832	1000000	2354.68579102		
<b>Internal Plating Total:</b>				<b>0.002832</b>	<b>1000000</b>	<b>2354.68579102</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001080	750000	897.973388672		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000360	250000	299.324462891		
<b>Die Attach Total:</b>				<b>0.001440</b>	<b>1000000</b>	<b>1197.29785156</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.194880	240000	162034.296875		
		Bromine (Br)	40039-93-8	0.008120	10000	6751.4296875		
		Silica (SiO2)	60676-86-0	0.584640	720000	486102.9375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.024360	30000	20254.2871094		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.812000</b>	<b>1000000</b>	<b>675142.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000642	1000000	533.795288086		
					<b>TOTAL MASS (g) :</b>	<b>1.202708</b>		